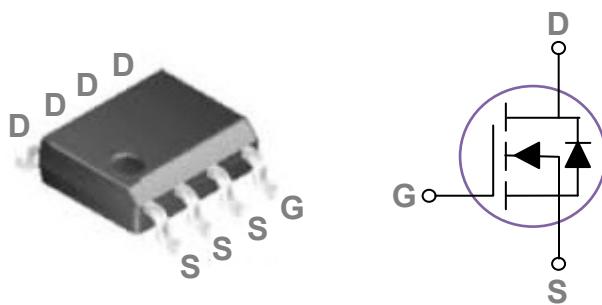


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOP8 Pin Configuration



BVDSS	RDS(ON)	ID
30V	10mΩ	15A

### Features

- 30V, 15A, RDS(ON)=10mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

### Applications

- Notebook
- Load Switch
- LED applications
- Hand-Held Device

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	15	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	9.5	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	60	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	4	W
	Power Dissipation – Derate above 25°C	0.032	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	31	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.04	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=6\text{A}$	---	8.5	10	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=3\text{A}$	---	12.5	15	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	1.2	1.6	2.5	V
			---	-4	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=10\text{A}$	---	18	---	S

**Dynamic and switching Characteristics**

$Q_g$	Total Gate Charge <sup>2, 3</sup>	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=10\text{A}$	---	7.5	15	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2, 3</sup>		---	1.3	3	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2, 3</sup>		---	4.5	9	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2, 3</sup>	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=3.3\Omega$ $I_D=15\text{A}$	---	4.8	9	ns
$T_r$	Rise Time <sup>2, 3</sup>		---	12.5	25	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2, 3</sup>		---	27.6	50	
$T_f$	Fall Time <sup>2, 3</sup>		---	8.2	16	
$C_{\text{iss}}$	Input Capacitance		---	750	1350	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	150	300	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	110	200	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	2.7	4.5	$\Omega$

**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	15	A
$I_{\text{SM}}$	Pulsed Source Current		---	---	30	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

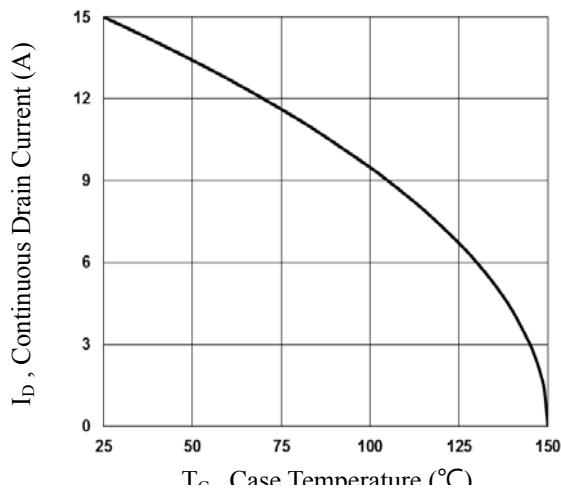


Fig.1 Continuous Drain Current vs.  $T_c$

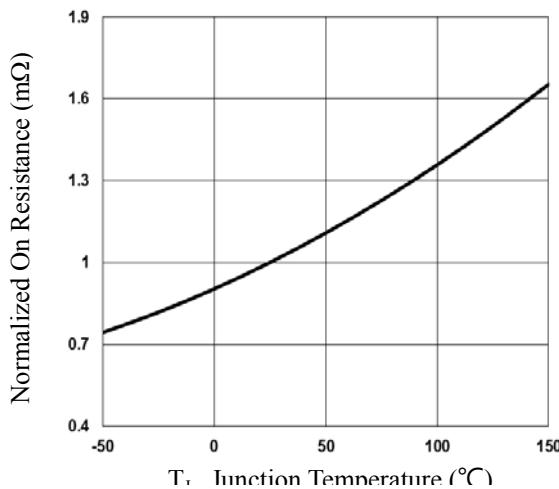


Fig.2 Normalized R<sub>DS(on)</sub> vs.  $T_j$

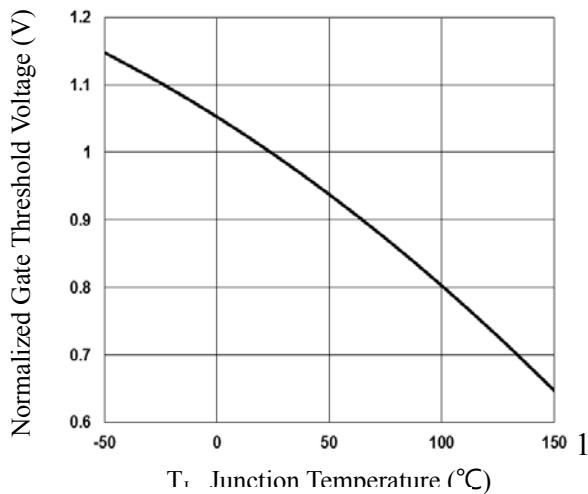


Fig.3 Normalized  $V_{th}$  vs.  $T_j$

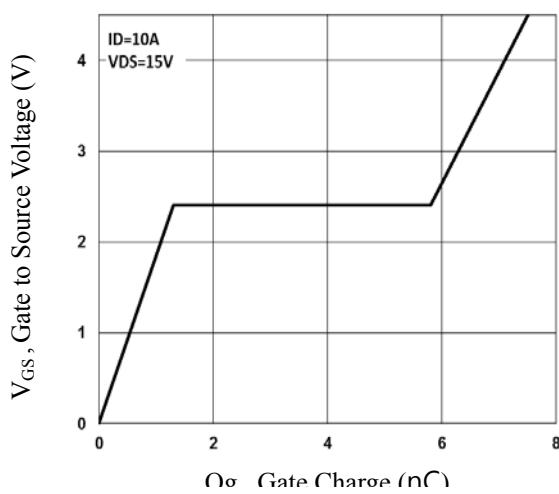


Fig.4 Gate Charge Waveform

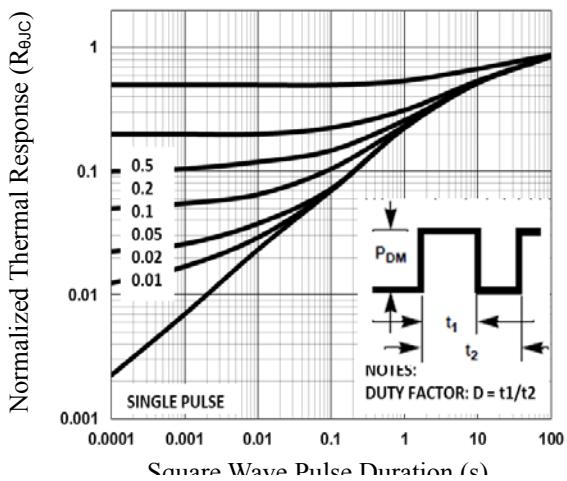


Fig.5 Normalized Transient Impedance

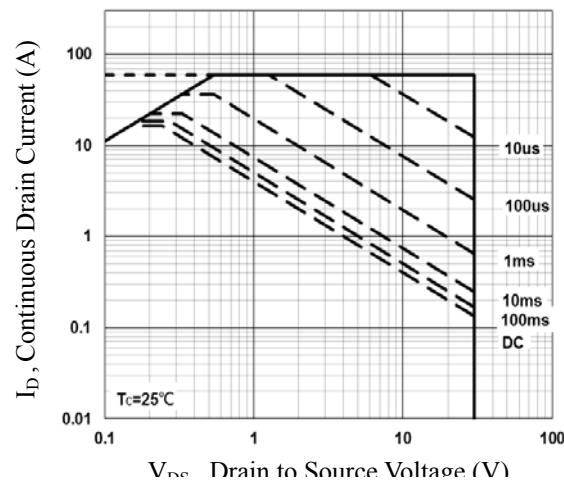


Fig.6 Maximum Safe Operation Area

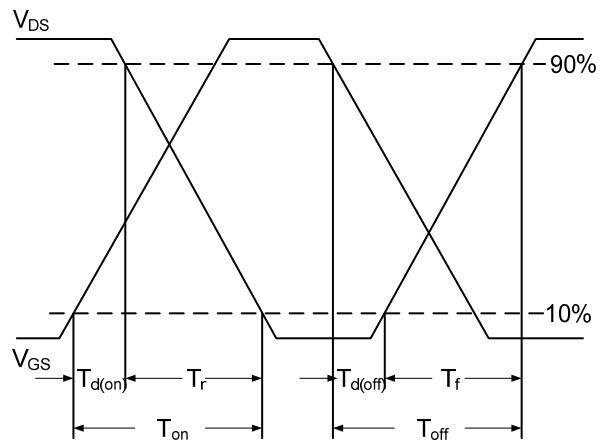


Fig.7 Switching Time Waveform

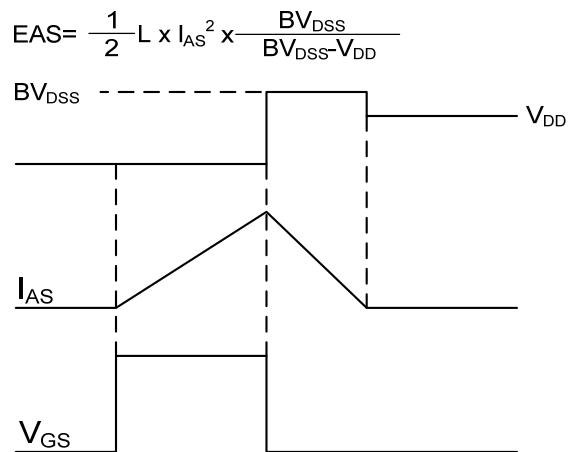
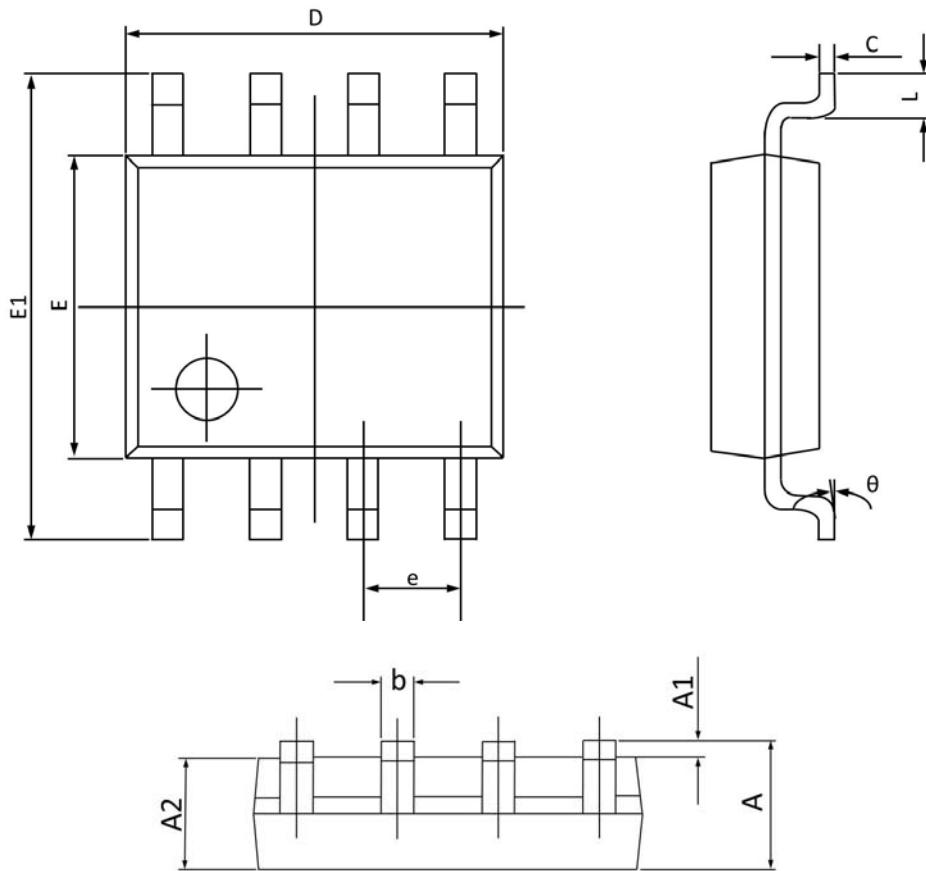


Fig.8 EAS Waveform

## SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.750	1.350	0.069	0.053
A1	0.250	0.100	0.010	0.004
A2	1.500	1.300	0.059	0.051
b	0.490	0.350	0.019	0.014
C	0.260	0.190	0.010	0.007
D	5.100	4.700	0.201	0.185
E	4.100	3.700	0.161	0.146
E1	6.200	5.800	0.244	0.228
e	1.27BSC		0.05BSC	
L	0.900	0.400	0.035	0.016
θ	8°	0°	8°	0°